

NCE P-Channel **Super Trench** Power MOSFET

Description

The NCEP40PT30VD uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

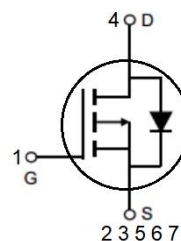
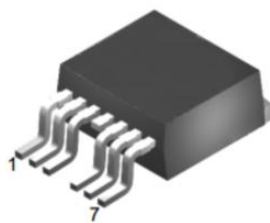
Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = -40V, I_D = -300A$
 $R_{DS(ON)} = 1.6m\Omega$, typical@ $V_{GS} = -10V$
 $R_{DS(ON)} = 2.2m\Omega$, typical@ $V_{GS} = -4.5V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested
- 100% ΔV_{ds} tested

TO-263-7L



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP40PT30VD	NCEP40PT30VD	TO-263-7L	-	-	-

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-300	A
Drain Current-Continuous($T_c = 100^\circ C$)	$I_D (100^\circ C)$	-210	A
Pulsed Drain Current	I_{DM}	-1200	A
Maximum Power Dissipation	P_D	390	W
Derating factor		2.63	W/ $^\circ C$
Single pulse avalanche energy ^(Note 1)	E_{AS}	2400	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.38	$^\circ C/W$
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Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-40		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.6	-2.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-20A	-	1.6	2.3	mΩ
		V _{GS} =-4.5V, I _D =-20A	-	2.2	3.0	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-10V, I _D =-20A	-	80	-	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V, F=1.0MHz	-	15148	-	PF
Output Capacitance	C _{oss}		-	3900	-	PF
Reverse Transfer Capacitance	C _{rss}		-	90	-	PF
Switching Characteristics <small>(Note 2)</small>						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-20V, I _D =-20A V _{GS} =-10V, R _G =1.6Ω	-	45	-	nS
Turn-on Rise Time	t _r		-	50	-	nS
Turn-Off Delay Time	t _{d(off)}		-	140	-	nS
Turn-Off Fall Time	t _f		-	45	-	nS
Total Gate Charge	Q _g	V _{DS} =-20V, I _D =-75A, V _{GS} =-10V	-	208.8	-	nC
Gate-Source Charge	Q _{gs}		-	41.6		nC
Gate-Drain Charge	Q _{gd}		-	27		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-20A	-		-1.2	V
Diode Forward Current	I _S		-	-	-300	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =-20A	-	78	-	nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs	-	200	-	nC

Notes:

1. EAS condition : T_J=25°C, V_{DD}=-20V, V_G=-10V, L=0.5mH, R_G=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C. The SOA curve provides a single pulse rating.

Typical Electrical and Thermal Characteristics

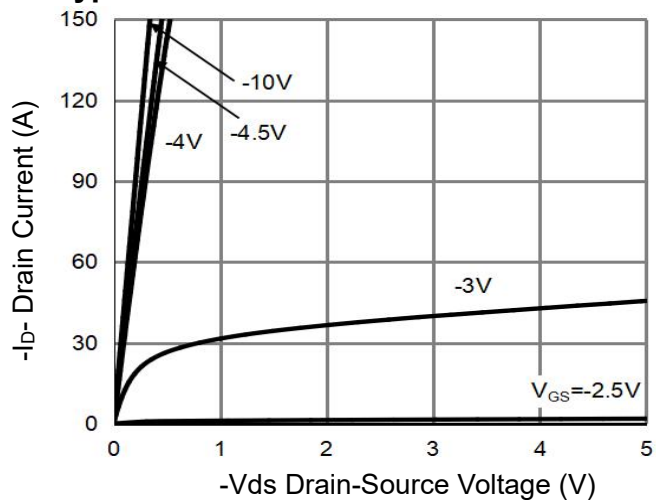


Figure 1 Output Characteristics

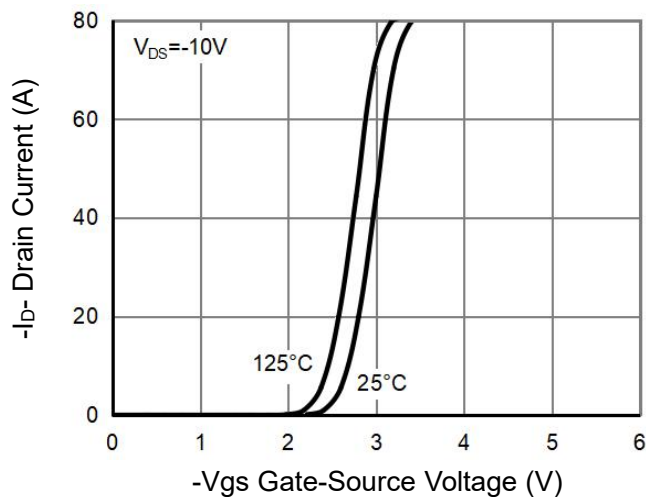


Figure 2 Transfer Characteristics

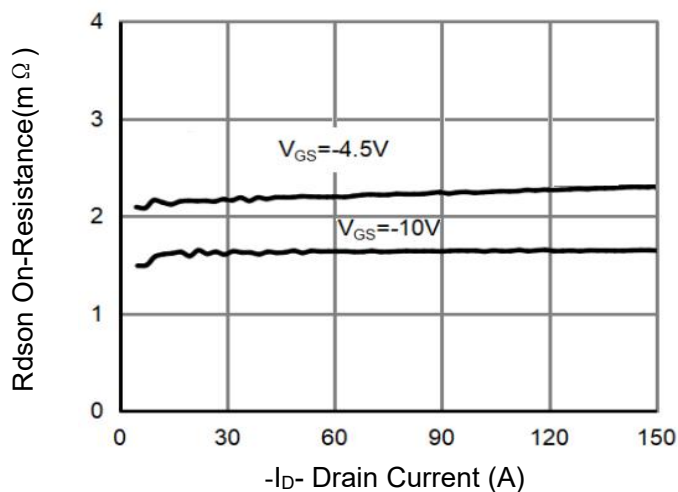


Figure 3 Rdson- Drain Current

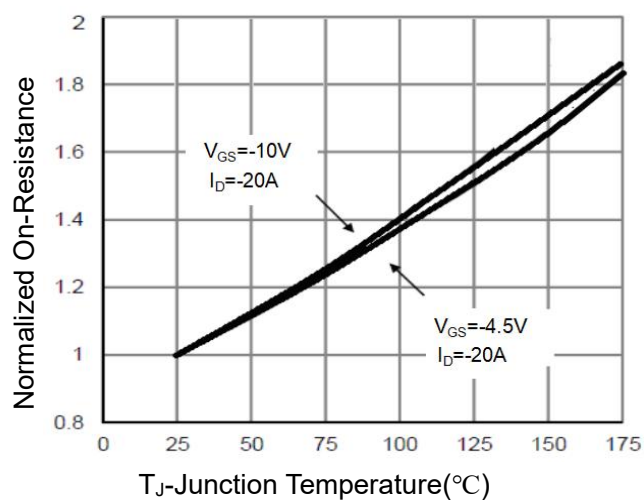


Figure 4 Rdson-Junction Temperature

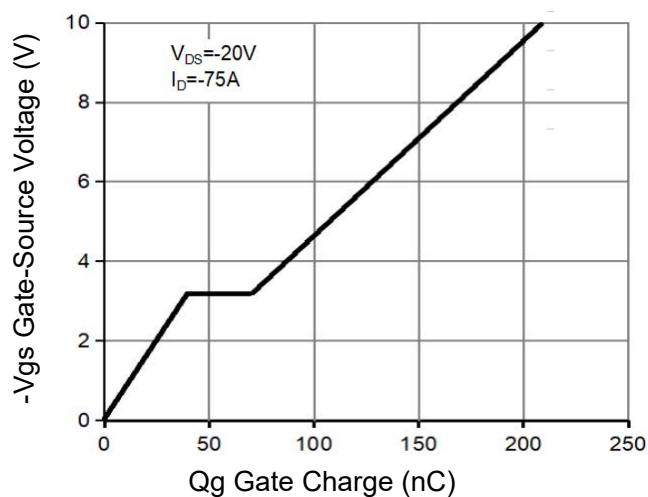


Figure 5 Gate Charge

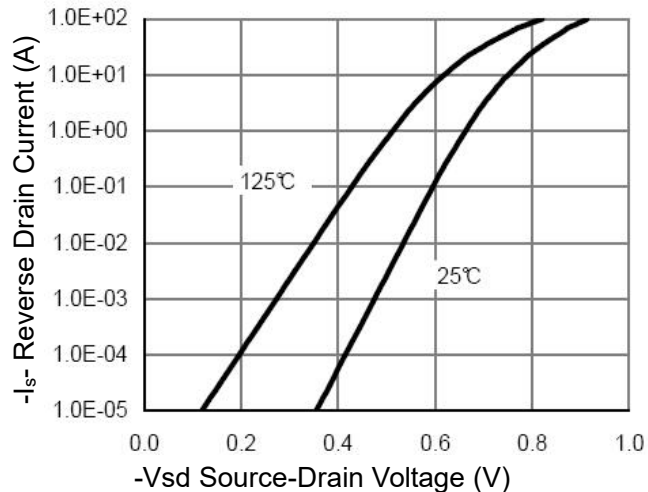


Figure 6 Source- Drain Diode Forward

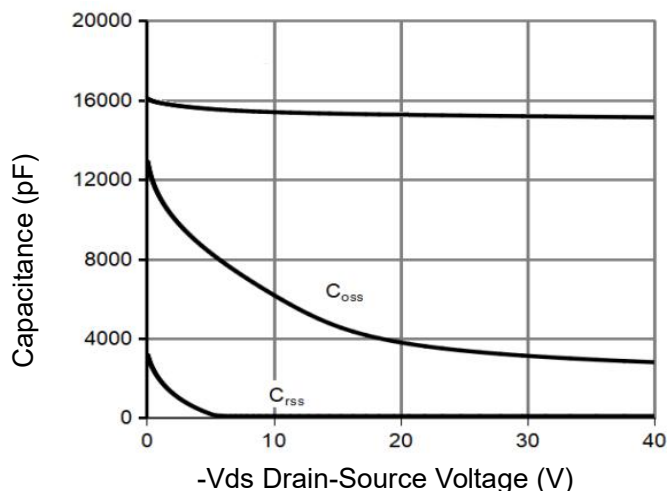


Figure 7 Capacitance vs Vds

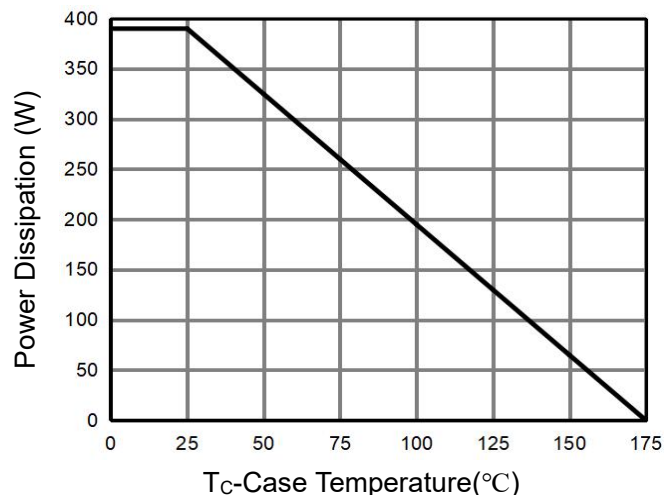


Figure 9 Power De-rating

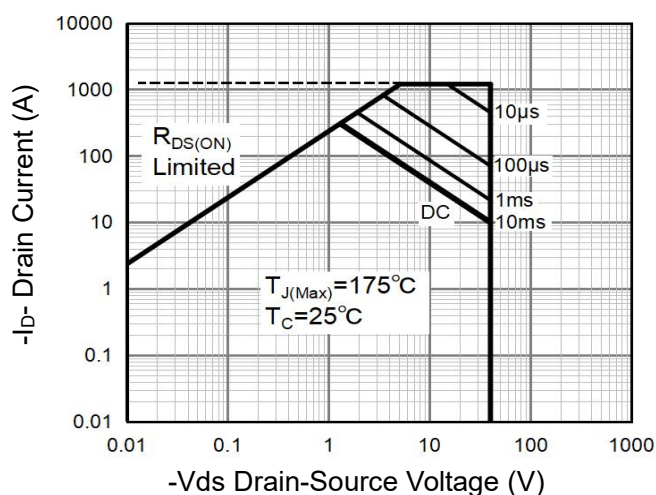


Figure 8 Safe Operation Area (Note3)

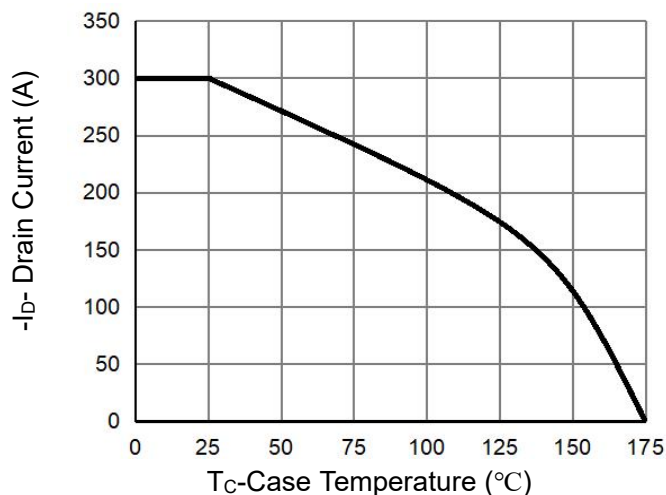


Figure 10 Current De-rating

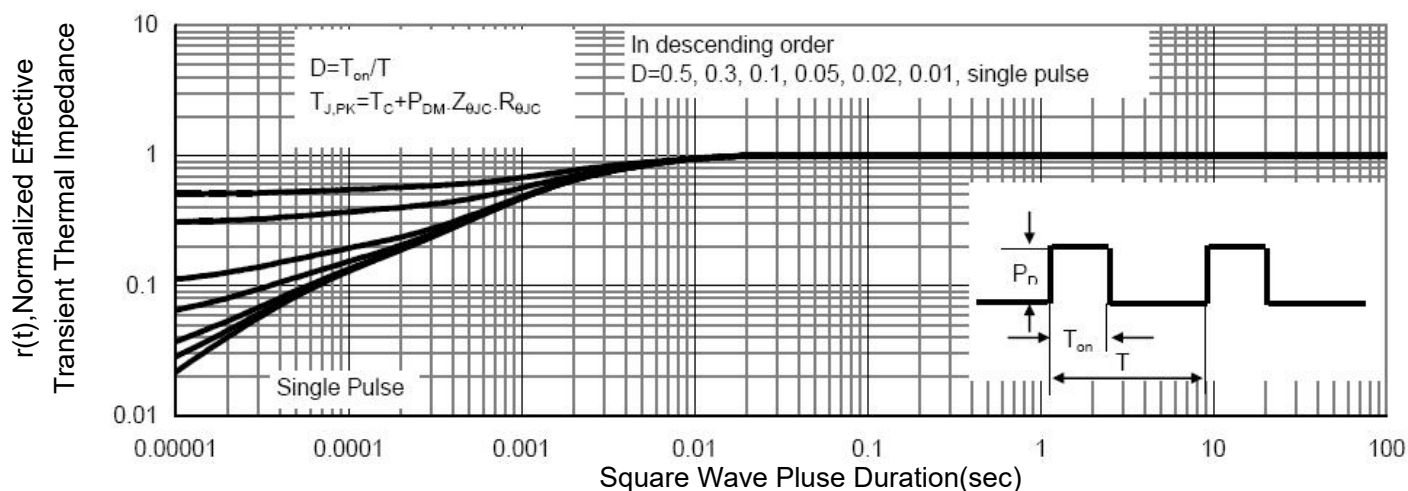
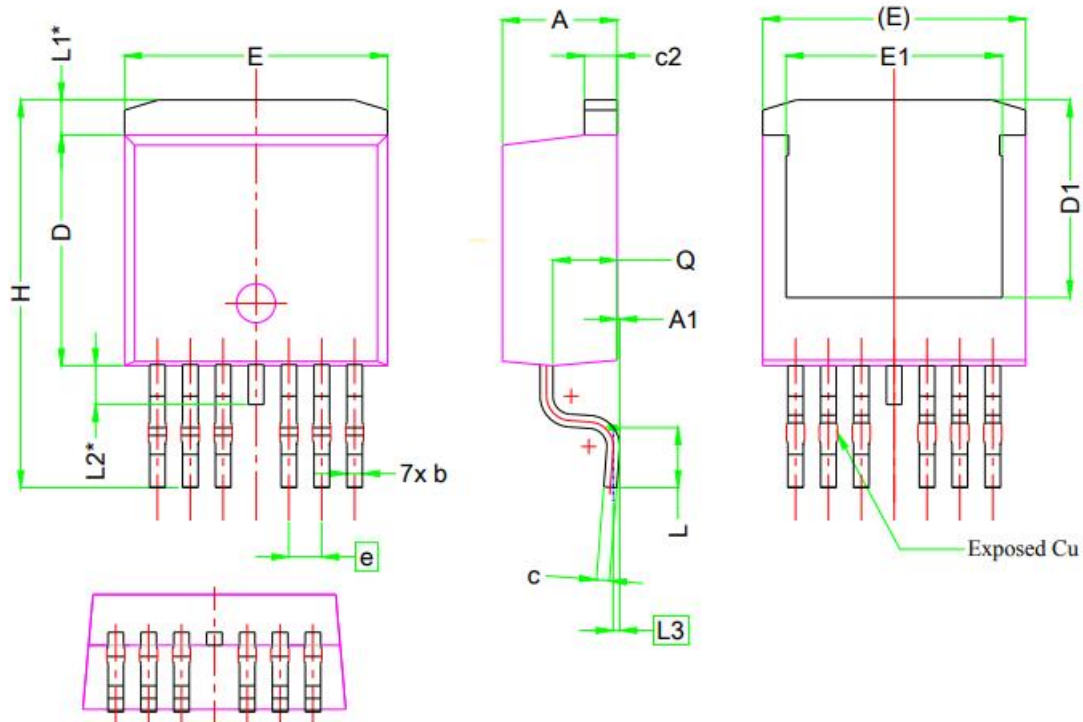
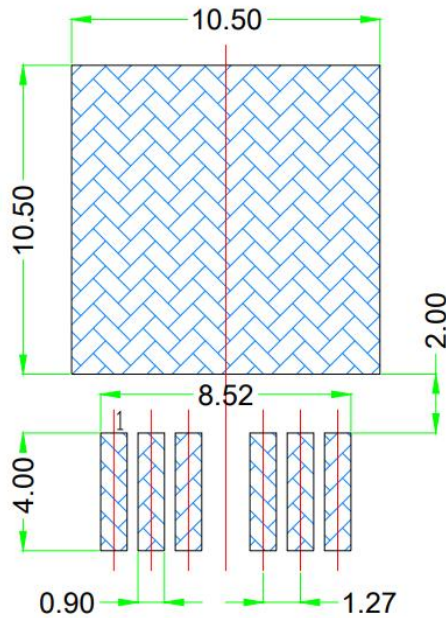


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-263-7L Package Information



Land Pattern
(Only for Reference)



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	---
E	9.96	10.16	10.36
E1	8.20	8.35	8.50
e	1.27 BSC		
H	14.61	15.00	15.88
L	1.78	2.32	2.79
L1	1.36 REF.		
L2	1.50 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

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